

**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) An apparatus for metal electroplating, comprising:  
a ~~electroplating~~ an electroplating tank for containing an electrolyte at a first temperature;  
a substrate holder for holding a semiconductor substrate; and  
a heater for heating the portion of the electrolyte adjacent to the substrate holder to a second temperature higher than the first temperature,  
wherein the heater comprises two individual thermal insulating supports respectively having a heating element thereon and an opening formed between the two insulating supports for allowing the electrolyte to flow therethrough, and  
wherein the heater is independently disposed in the electroplating tank and in a position opposite to the substrate holder, and the heater provides no fluid into the electroplating tank.
- 2-3. (Cancelled)
4. (Original) The apparatus as claimed in claim 1, wherein a temperature difference of about 5 to 60 °C exists between the second temperature and the first temperature.
5. (Original) The apparatus as claimed in claim 1, wherein the second temperature is about 27 to 80 °C.
6. (Original) The apparatus as claimed in claim 1, wherein the electrolyte comprises Cu ions.

Application No. 10/814,175  
Amendment dated July 28, 2008  
After Final Office Action of May 27, 2008

Docket No.: 0941-0940PUS1

7-23. (Cancelled)